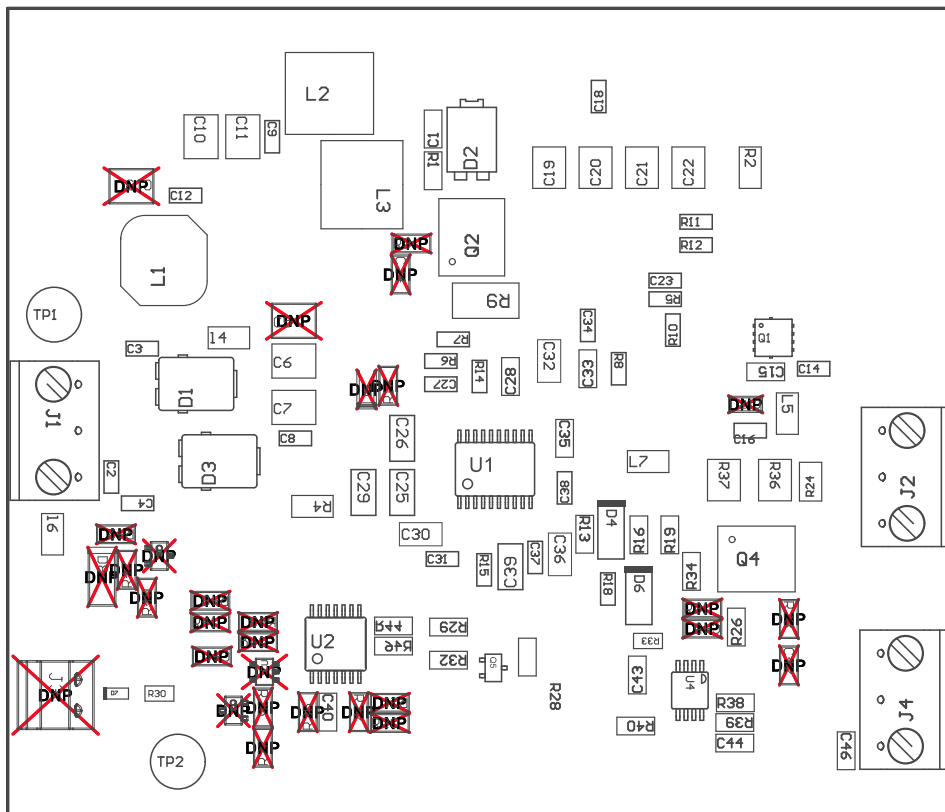


Z21 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z22 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z23 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: Only Populated

PCB VIEWED FROM TOP SIDE	BOARD #: XX####	REV: E1	SUN REV: Not In VersionControl
	TID #: N/A		
PLOT NAME = Top Assembly Drawing	GENERATED : 2/2/2018	4:08:02 PM	TEXAS INSTRUMENTS

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